

TSMC-00-143



1763

March 28, 2001

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 09/669,159 09/25/00 |  
| H. W. CHEN ET AL

"AN IN-SITU STRIP PROCESS FOR  
POLYSILICON ETCHING IN DEEP  
SUB-MICRON TECHNOLOGY"

Grp. Art Unit: 1763 G. GOUDREAU

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated December 28, 2000,  
please amend the above identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patent and Trademarks, Washington, D.C. 20231, on March 28, 2001.

Rosemary L. S. Pike, Reg. No. 39,332

Signature Rosemary L. S. Pike  
Date March 28, 2001

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